



Semiconductor Device Type: G3X-SSOP-20-.209in-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				12.32	100.00%	7.50%		
	Silicon	7440-21-3	12.32		100.00%		7.50%	75030
Plating and Anode Ball				2.05	100.00%	1.25%		
	Miscellaneous	Trade Secret	0.00		0.10%		0.00%	12
	Tin	7440-31-5	2.05		99.90%		1.25%	12472
Bond Wire				0.33	100.00%	0.20%		
	Gold	7440-57-5	0.33		100.00%		0.20%	2010
Mold Compound				131.03	100.00%	79.80%		
	Carbon Black	1333-86-4	0.66		0.50%		0.40%	3990
	Phenolic Resin	Trade Secret	10.48		8.00%		6.38%	63839
	Silica (Fused)	60676-86-0	105.48		80.50%		64.24%	642382
	Epoxy Resin	Trade Secret	10.48		8.00%		6.38%	63839
	o-Cresol-epichlorohydrin-formaldehyde Copolymer	29690-82-2	3.93		3.00%		2.39%	23940
Lead Frame				16.15	100.00%	9.84%		
	Lead	7439-92-1	0.00		0.00%		0.00%	5
	Copper	7440-50-8	15.74		97.46%		9.59%	95884
	Zinc	7440-66-6	0.02		0.12%		0.01%	118
	Phosphorus	7723-14-0	0.01		0.08%		0.01%	77
	Iron	7439-89-6	0.38		2.33%		0.23%	2296
Lead Frame Plating				1.09	100.00%	0.66%		
	Silver	7440-22-4	1.09		100.00%		0.66%	6615
Die Attach				1.23	100.00%	0.75%		
	Formaldehyde, Polymer with 2-(chloromethyl)oxirane and Phenol	9003-36-5	0.12		10.00%		0.07%	749
	2,2'-[[2-(2-Oxiranylmethoxy)-1,3-phenylene]bis(methylene)]bis[oxirane]	13561-08-5	0.12		10.00%		0.07%	749
	Silver	7440-22-4	0.86		70.00%		0.52%	5244
	Dimer Acid Diglycidyl Ester	68475-94-5	0.12		10.00%		0.07%	749
Totals			164.20	164.20		100.00%	100.00%	1000000

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